

### AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A ~~fabrication~~ cooling apparatus for a wafer baking  
5 plate having a support plate for supporting a wafer, a heater under the support plate, and  
a heat transfer plate interposed between the support plate and the heater, for transferring  
heat, comprising:

a hollow bore formed in the heat transfer plate and partially filled with a liquid  
working fluid; and

10 a cooling pipe laid in the heat transfer plate, for circulating a cooling medium

2. (Currently Amended) The ~~fabrication~~ cooling apparatus of claim 1,  
wherein the cooling pipe is laid in the hollow bore of the heat transfer plate and disposed  
in the working fluid which is liquid at room temperature.

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3. (Currently Amended) The ~~fabrication~~ cooling apparatus of claim 1,  
wherein a groove is formed in the bottom of the hollow bore and the cooling pipe is laid  
in the groove.

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4. (Currently Amended) The ~~fabrication~~ cooling apparatus of claim 1,  
wherein the cooling pipe is laid outside the hollow bore.

5. (Currently Amended) The ~~fabrication~~ cooling apparatus of claim 1,  
wherein the cooling pipe includes a first pipe laid in the hollow bore and a second pipe  
25 laid outside the hollow bore.

6. (Currently Amended) The ~~fabrication~~ cooling apparatus of claim 1,  
wherein a cross-section of the cooling pipe is one of circular, oval, and polygonal.